

SKM 200 MLI 066 T



SEMITRANS[®] 5

Trench IGBT Modules

SKM 200 MLI 066 T

Target Data

Features

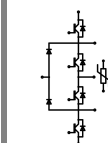
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- Integrated NTC temperature sensor

Typical Applications

- UPS
- 3 Level Inverter

Remarks

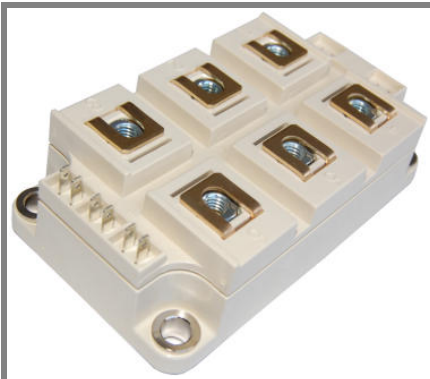
- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recommended $T_{op} = -40..+150^\circ\text{C}$



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Absolute Maximum Ratings		$T_{case} = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values	Units	
IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$	600	V	
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	280	A
		$T_c = 80^\circ\text{C}$	210	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	400	A	
V_{GES}		± 20	V	
t_{psc}	$V_{CC} = 360\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 600\text{ V}$	6	μs	
Inverse Diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	270	A
		$T_c = 80^\circ\text{C}$	200	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	400	A	
I_{FSM}	$t_p = 10\text{ ms};$ half sine wave $T_j = 150^\circ\text{C}$	1310	A	
Freewheeling Diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	270	A
		$T_c = 80^\circ\text{C}$	200	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$	400	A	
I_{FSM}	$t_p = 10\text{ ms};$ half sine wave $T_j = 150^\circ\text{C}$	1310	A	
Module				
$I_{t(RMS)}$		500	A	
T_{vj}		- 40 ... + 175	$^\circ\text{C}$	
T_{stg}		- 40 ... + 125	$^\circ\text{C}$	
V_{isol}	AC, 1 min.	2500	V	

Characteristics		$T_{case} = 25^\circ\text{C}$, unless otherwise specified				
Symbol	Conditions	min.	typ.	max.	Units	
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 3,2\text{ mA}$	5	5,8	6,5	V	
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$ $T_j = 25^\circ\text{C}$			0,01	mA	
I_{GES}	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}$ $T_j = 25^\circ\text{C}$			1200	nA	
V_{CE0}			$T_j = 25^\circ\text{C}$	0,9	1	V
			$T_j = 150^\circ\text{C}$	0,7	0,8	V
r_{CE}	$V_{GE} = 15\text{ V}$		$T_j = 25^\circ\text{C}$	2,7	4,5	$\text{m}\Omega$
			$T_j = 150^\circ\text{C}$	5	6,5	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 200\text{ A}, V_{GE} = 15\text{ V}$		$T_j = 25^\circ\text{C}_{chiplev.}$	1,45	1,9	V
			$T_j = 150^\circ\text{C}_{chiplev.}$	1,7	2,1	V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		12,3		nF
C_{oes}				0,76		nF
C_{res}				0,36		nF
R_{Gint}	$T_j = ^\circ\text{C}$		1		Ω	
$t_{d(on)}$	$R_{Gon} = 2,4\ \Omega$	$V_{CC} = 300\text{ V}$ $I_C = 200\text{ A}$	$T_j = 150^\circ\text{C}$	$V_{GE} = -8\text{ V}/+15\text{ V}$		ns
t_r						ns
E_{on}						mJ
$t_{d(off)}$	$R_{Goff} = 2,4\ \Omega$		$T_j = 150^\circ\text{C}$	$V_{GE} = -8\text{ V}/+15\text{ V}$		ns
t_f						ns
E_{off}						mJ
$R_{th(j-c)}$	per IGBT		0,21			K/W



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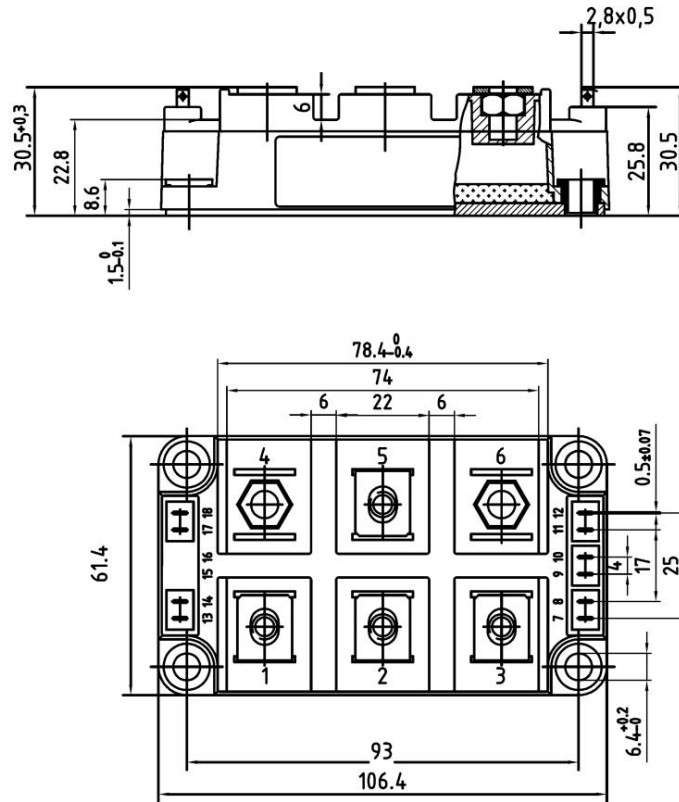
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Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 200\text{ A}; V_{GE} = 0\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,4	1,6	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	1,4	1,6	V
V_{F0}		$T_j = 25^\circ\text{C}$	0,95	1	V
		$T_j = 150^\circ\text{C}$	0,85	0,9	V
r_F		$T_j = 25^\circ\text{C}$	2	3	mΩ
		$T_j = 150^\circ\text{C}$	2,7	3,5	mΩ
I_{RRM}	$I_F = 200\text{ A}$				A
Q_{rr}					μC
E_{rr}	$V_{GE} = -8\text{ V}; V_{CC} = 300\text{ V}$				mJ
$R_{th(j-c)D}$	per diode		0,39		K/W
Free-wheeling diode (Neutral Clamp Diode)					
$V_F = V_{EC}$	$I_{Fnom} = 200\text{ A}; V_{GE} = 0\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,4	1,6	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	1,4	1,6	V
V_{F0}		$T_j = 25^\circ\text{C}$	0,95	1	V
		$T_j = 150^\circ\text{C}$	0,85	0,9	V
r_F		$T_j = 25^\circ\text{C}$	2	3	V
		$T_j = 150^\circ\text{C}$	2,7	3,5	V
I_{RRM}	$I_F = 200\text{ A}$				A
Q_{rr}					μC
E_{rr}	$V_{GE} = 0\text{ V}; V_{CC} = 600\text{ V}$				mJ
$R_{th(j-c)FD}$	per diode		0,39		K/W
M_s	to heat sink M6	3		5	Nm
M_t	to terminals M6	2,5		5	Nm
w				310	g
Temperature sensor					
R_{100}	$T_s = 100^\circ\text{C}$ ($R_{25} = 5\text{ k}\Omega$)		493±5%		Ω
					K

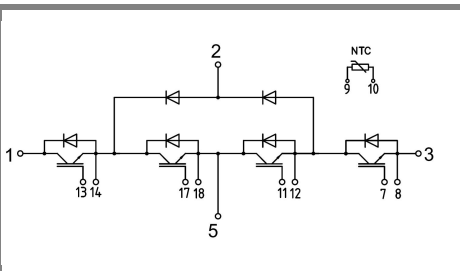
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

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Case D60



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Case D60